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## For Immediate Release

**TOKYO, JAPAN, December 1, 2003**

Petaluma, California based Xandex, Inc. will introduce and display its revolutionary new Xandex Zero Insertion Force (XZIF) interconnect solution for semiconductor test interfacing at SEMICON Japan, December 3-5 2003, booth 9-B306.

### **Introducing the XZIF Interconnect**

The XZIF interconnect is an innovative design solution to the challenges of high pin count semiconductor test interfacing that reduces total interface costs. A radical departure from traditional spring probe compliant connections and backplane connectors, the XZIF interconnect design utilizes cutting edge "bump on flex" technology to replace both spring probes and pin/socket connectors. Already selected by a leading ATE manufacturer for a next generation test system, XZIF offers significant cost savings over traditional interconnect systems and provides the higher densities and parallelism required by next generation ATE platforms.

### **The XZIF Advantage**

As demand for greater interconnect density and parallelism in tester to Device Under Test (DUT) board interfacing has increased, especially in memory test platforms, the cost of the interface has risen and so has the compression force required to complete connections. Greater compression force has, in turn, increased DUT board complexity and flatness

requirements, which are driving board costs higher with each new generation of test platforms.

The XZIF interconnect resolves all of these challenges. Ideally suited to high-density memory test applications, XZIF “bump on flex” pitches enable higher channel densities at a lower cost per channel than spring probes will ever allow. With compression forces minimized, XZIF eliminates DUT board deflection and alignment issues and also the need for expensive board stiffeners.

XZIF reduces compliant connection costs by 50% over spring probe interfaces with the same pin count. Gold bumps ensure a reliable and durable contact that provides over 5,000 interconnect cycles. Because there is no spring probe compression required, XZIF exhibits extremely reliable contact resistance without the need for a high force mechanical or vacuum coupling mechanism.

### **Electrical Performance**

The first generation of the impedance controlled 50 Ohm XZIF interconnect has bandwidth of >1 GHz at -3 dB, <10 mOhm contact resistance and current rating of 1A.

For more information about the new XZIF interconnect and the complete line of Xandex Transmission Line Solutions, visit the Xandex sales team in booth #9-B306 at Semicon Japan or see us on the Internet at [www.xandex.com](http://www.xandex.com).

### **About Xandex**

Xandex, Inc. provides innovative test solutions to the semiconductor industry. It is the world's leading supplier of semiconductor wafer marking solutions and a leading third-party supplier of test interface products to Automatic Test Equipment manufacturers. The Company serves over 1000 semiconductor wafer sort floors in 27 countries worldwide. The Xandex product lines include DieMark® Inking Systems, ATE Interface and Docking solutions and Xandex Transmission Line (XTL) cables and connectors. The Company is ISO 9001:2000 registered and maintains multiple patents for its products. Xandex manufactures and distributes its products throughout North America and Europe from its corporate headquarters and manufacturing facility in Petaluma, California and has distributors for regional sales and customer support operations throughout Asia. More company information can be found at [www.xandex.com](http://www.xandex.com).

